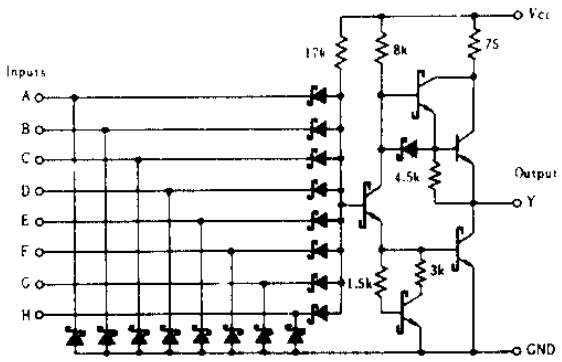
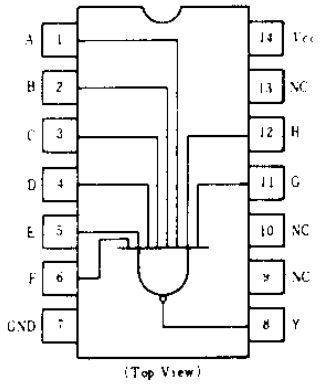
HD74LS30 ●8-input Positive NAND Gate

■CIRCUIT SCHEMATIC



■PIN ARRANGEMENT



■ELECTRICAL CHARACTERISTICS ($Ta = -20 \sim +75°C$)

Item	Symbol	Test Conditions		min	typ*	max	Unit
Input voltage	V_{IH}			2.0	—	—	V
	V_{IL}			—	—	0.8	V
Output voltage	V_{OH}	$V_{CC}=4.75V$, $V_{IL}=0.8V$, $I_{OH}=-400\mu A$		2.7	—	—	V
	V_{OL}	$V_{CC}=4.75V$, $V_{IH}=2V$	$I_{OL}=8mA$	—	—	0.5	V
			$I_{OL}=4mA$	—	—	0.4	
Input current	I_{IH}	$V_{CC}=5.25V$, $V_I=2.7V$		—	—	20	μA
	I_{IL}	$V_{CC}=5.25V$, $V_I=0.4V$		—	—	−0.4	mA
	I_I	$V_{CC}=5.25V$, $V_I=7V$		—	—	0.1	mA
Short-circuit output current	I_{OS}	$V_{CC}=5.25V$		−20	—	−100	mA
Supply current	I_{CCH}	$V_{CC}=5.25V$		—	0.35	0.5	mA
	I_{CCL}			—	0.6	1.1	
Input clamp voltage	V_{IK}	$V_{CC}=4.75V$, $I_{IN}=-18mA$		—	—	−1.5	V

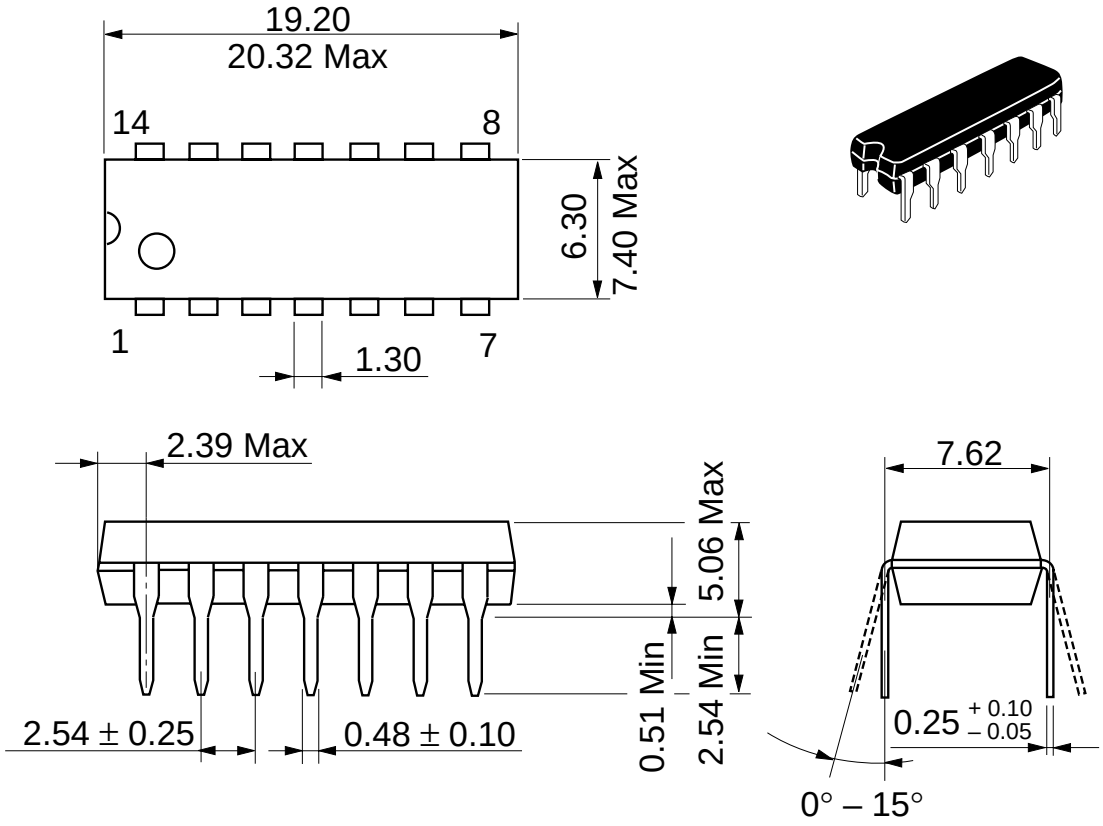
* V_{CC}=5V, Ta=25°C

■SWITCHING CHARACTERISTICS ($V_{CC}=5V$, $Ta=25°C$)

Item	Symbol	Test Conditions	min	typ	max	Unit
Propagation delay time	t_{PLH}	$C_L=15pF$, $R_L=2k\Omega$	—	8	15	ns
	t_{PHL}		—	13	20	

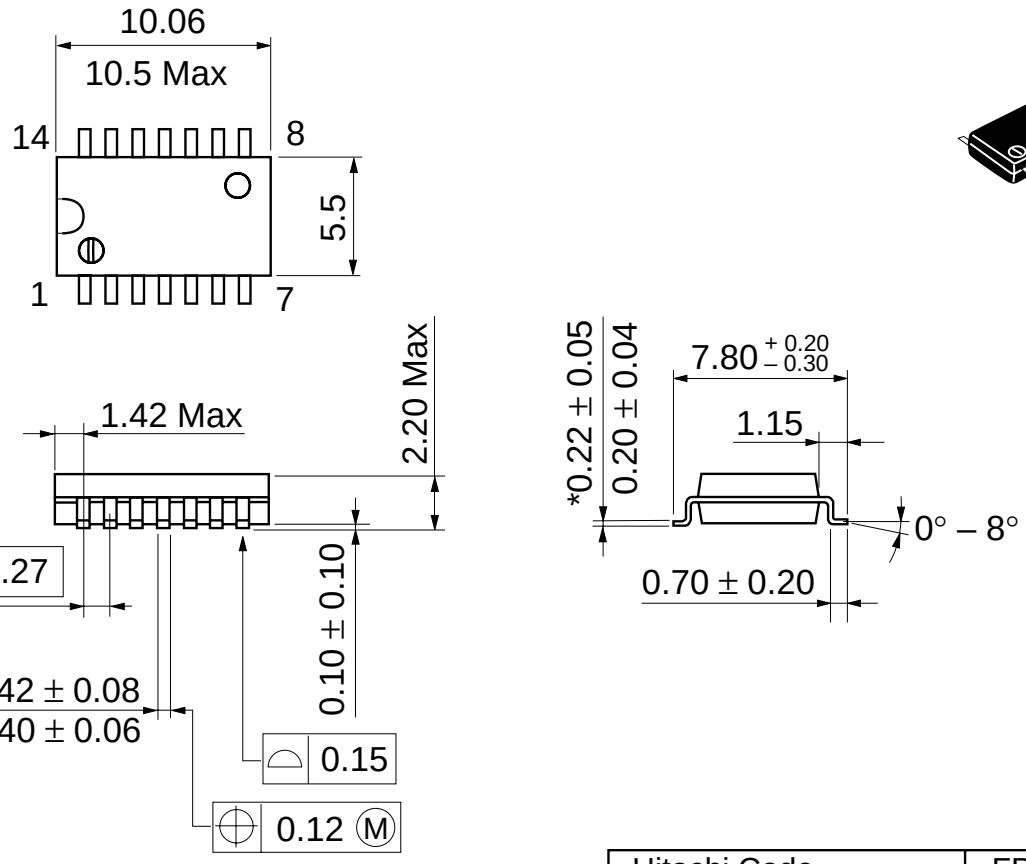
Note) Refer to Test Circuit and Waveform of the Common Item

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

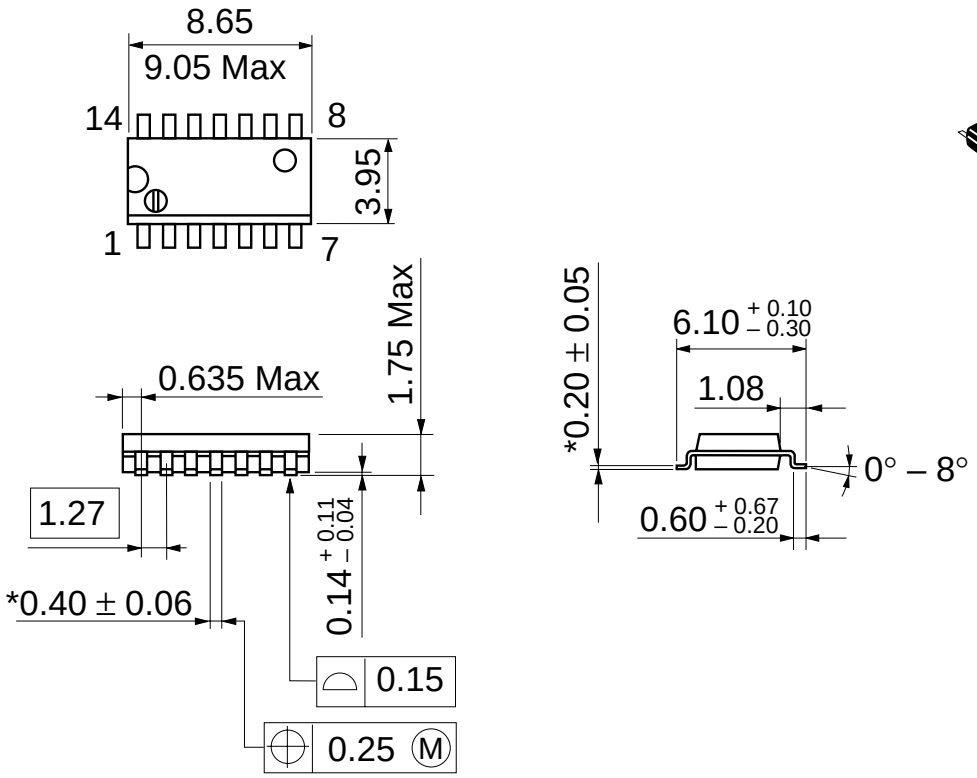
Unit: mm

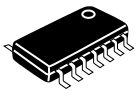


*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g

Unit: mm





*Pd plating

Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

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